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Space product assurance - Repair and modification of printed circuit board assemblies for space use; English version EN 16602-70-28:2014

Content	page
Foreword	9
1 Scope	10
2 Normative references	11
3 Terms, definitions and abbreviated terms	12
3.1 Terms from other standards	12
3.2 Terms specific to the present standard	12
3.3 Abbreviated terms	13
4 Requirements	14
4.1 Basic requirements.....	14
4.1.1 Hazard, health and safety precautions	14
4.1.2 Materials	14
4.1.3 Facilities.....	14
4.1.4 General.....	14
4.2 Repairs	15
4.2.1 Repair criteria	15
4.2.2 Number of repairs.....	15
4.3 Modifications	15
4.3.1 Modification criteria.....	15
4.3.2 Number of modifications.....	16
4.4 Rework	16
4.4.1 Rework criteria.....	16
4.4.2 Number of reworks	16
4.5 Other requirements	16
4.6 Removal of conformal coating.....	17
4.6.1 Requirements	17
4.6.2 Procedure	17
4.6.3 Acceptance criteria.....	17

4.7	Solder joint removal and unclenching	18
4.7.1	Procedure	18
4.7.2	Acceptance criteria	18
4.8	Repair of damaged gold-plated areas	18
4.8.1	Requirements	18
4.8.2	Procedure	18
4.8.3	Acceptance criteria	19
4.9	Repair of damaged conductor tracks.....	19
4.9.1	Requirements	19
4.9.2	Procedure	19
4.9.3	Acceptance criteria	20
4.10	Repair of lifted conductors.....	20
4.10.1	Requirements	20
4.10.2	Procedure	20
4.10.3	Acceptance criteria	20
4.11	Repair of lifted terminal areas (pads)	21
4.11.1	Requirements	21
4.11.2	Procedure	21
4.11.3	Acceptance criteria	21
4.12	Terminal post replacement.....	21
4.12.1	Requirements	21
4.12.2	Procedure	21
4.12.3	Acceptance criteria	21
4.13	Wire-to-wire joints.....	22
4.13.1	Requirements	22
4.13.2	Procedure	22
4.13.3	Acceptance criteria	22
4.14	Addition of components	22
4.14.1	Requirements	22
4.14.2	Procedure	23
4.14.3	Acceptance criteria	23
4.15	Removal and replacement of axial and multi-lead components	24
4.15.1	Requirements	24
4.15.2	Procedure	24
4.15.3	Acceptance criteria	24
4.16	Removal and replacement of flat-pack components	24
4.16.1	Requirements	24
4.16.2	Procedure	24

4.16.3	Acceptance criteria	25
4.17	Modification of component connections	25
4.17.1	Requirements	25
4.17.2	Procedure	25
4.17.3	Acceptance criteria	26
4.18	Cutting of internal track of a multi-layer printed circuit board	26
4.18.1	Procedure	26
4.18.2	Acceptance criteria	26
4.19	Quality assurance	26
4.19.1	General	26
4.19.2	Data	26
4.19.3	Nonconformance	27
4.19.4	Calibration	27
4.19.5	Traceability	27
4.19.6	Operator and inspector training and certification	27
Annex A (informative)	Removal of conformal coating	28
A.1	Introduction	28
A.2	Tools and materials	28
A.3	Methods for the removal of conformal coating	28
A.3.1	Method for the removal of polyurethane and silicone-type coating	28
A.3.2	Method for the removal of epoxy-type coating	29
Annex B (informative)	Solder joint removal and unclenching	31
B.1	Introduction	31
B.2	Tools and materials	31
B.3	Methods for solder joint removal and unclenching	31
B.3.1	Method for solder extraction with continuous vacuum	31
B.3.2	Method for solder extraction using sucker	32
B.3.3	Method for hot jet extraction	33
B.3.4	Method for the use of wicking braid	33
B.3.5	Method for unclenching of leads	34
Annex C (informative)	Repair of damaged gold-plated areas	35
C.1	Introduction	35
C.2	Tools and materials	35
C.3	Methods for the repair of damaged gold-plated areas	35
C.3.1	Method for the removal of solder splatter on gold plating	35
Annex D (informative)	Repair of damaged conductor tracks	36
D.1	Introduction	36

D.2	Tools and materials	36
D.3	Method for the repair of damaged conductor tracks.....	36
Annex E (informative) Repair of lifted conductors		37
E.1	Introduction.....	37
E.2	Tools and materials	37
E.3	Methods for repair of lifted conductors	38
E.3.1	Method for the use of epoxy under conductor	38
E.3.2	Method for the use of epoxy over conductor	38
Annex F (informative) Repair of lifted terminal areas (pads).....		39
F.1	Introduction.....	39
F.2	Tools and materials	40
F.3	Method for the repair of lifted terminal areas (pads).....	40
Annex G (informative) Terminal post replacement.....		41
G.1	Introduction.....	41
G.2	Tools and materials	41
G.3	Method for the replacement of terminal post.....	41
Annex H (informative) Wire-to-wire joints		43
H.1	Introduction.....	43
H.2	Tools and materials	43
H.3	Method for wire-to-wire joining	43
Annex I (informative) Addition of components		45
I.1	Introduction.....	45
I.2	Tools and materials	45
I.3	Methods for addition of components	46
I.3.1	Method for additional components mounted on reverse (non-component) side of board.....	46
I.3.2	Method for additional components mounted on component side of board	47
I.3.3	Method for additional components mounted on terminal posts, including “piggyback” mounting	48
I.3.4	Method for additional components mounted (on reverse side or on component side of board) using staking compound	49
I.3.5	Method for additional components mounted (on reverse side or on component side of board) to leads of adjacent components	50
I.3.6	Method for the addition of a wire link onto soldered chips on a single side piece of PCB with appropriate pads	55
I.3.7	Method for the addition of a wire link onto metallized cap of chips directly glued on PCB	56

Annex J (informative) Removal and replacement of axial and multi-lead components	57
J.1 Introduction.....	57
J.2 Tools and materials	57
J.3 Methods for removal and replacement of axial and multi-lead components	57
J.3.1 Method for the removal of components with axial leads (destructive removal)	57
J.3.2 Method for the removal of multi-lead components (destructive removal)...	58
Annex K (informative) Removal and replacement of flat-pack components.....	60
K.1 Introduction.....	60
K.2 Tools and materials	60
K.3 Method for the removal and replacement of flat-pack components.....	60
Annex L (informative) Modification of component connections	62
L.1 Introduction.....	62
L.2 Tools and materials	62
L.3 Methods for modification of component connections	62
L.3.1 Method for the soldering of a wrap-around connection to an extended component lead	62
L.3.2 Method for the soldering of component lead to a stud lead mounted into an existing hole.....	63
L.3.3 Method for mounting a dual-in-line (DIL) package with or without a wire link soldered onto a cropped lead	64
L.3.4 Method for mounting a connector with or without a wire link soldered onto a cropped lead.....	66
L.3.5 Method for the addition of a wire link into a plated-through hole occupied by a flat-section lead	67
L.3.6 Method for the addition of a wire link on top of a flat-pack lead	69
L.3.7 Method for the isolation of a component lead.....	69
L.3.8 Method for the addition of a wire link onto terminal pad of soldered chips.	71
Annex M (informative) Cutting of internal track of a multi-layer printed circuit board	73
M.1 Introduction.....	73
M.2 Tools and materials	73
M.3 Method for cutting the internal track of a multi-layer printed circuit board	73
Bibliography.....	75

Figures

Figure A-1 : Removal of coating by thermal parting device.....	30
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Figure B-1 : Continuous vacuum solder extraction on stud lead	32
Figure B-2 : Pulse-type solder sucker in use.....	32
Figure B-3 : Lifting individual leads with hot jet	33
Figure B-4 : Cross-sectional view of wicking method	34
Figure B-5 : Hot unclenching with thermal parting device	34
Figure E-1 : Lifted conductors	37
Figure E-2 : Repair using epoxy under conductor	38
Figure E-3 : Repair using epoxy over conductor	38
Figure F-1 : Lifted terminal area	39
Figure F-2 : Terminal areas without track.....	39
Figure F-3 : Terminal areas with track attached	40
Figure G-1 : Terminal post replacement.....	42
Figure H-1 : Use of approved type support clamp/heat sink	44
Figure I-1 : Additional components mounted on reverse (non-component) side of board.....	47
Figure I-2 : Additional components mounted on component side of board	48
Figure I-3 :“Piggyback” mounting of one component on top of another	49
Figure I-4 : Mounting and wiring of additional axially-leaded components mounted (on reverse side or on component side of board) using staking compound.....	51
Figure I-5 : Upside down mounting and wiring of additional side-brazed DIL component (on reverse side or on component side of board) using staking compound.....	52
Figure I-6 : Mounting of additional non-axially leaded components, e.g. capacitors, with wire connecting top or bottom sides of the circuit board using staking compound (on reverse side or on component side of board)	52
Figure I-7 : Mounting of additional component (on component side of board) with wire connections on reverse side of board using staking compound	53
Figure I-8 : Mounting of additional component (on reverse side of board) across extended leads of adjacent components	53
Figure I-9 : Mounting of additional component by linking to a “pigtailed” lead of an adjacent component	54
Figure I-10 : Mounting of additional component by linking to lead of an adjacent transistor (or other large component).....	55
Figure I-11 : Addition of a wire link onto metallized cap of chips directly glued on PCB	56
Figure J-1 : Removal of multi-lead components, clipping of component leads	58
Figure J-2 : Removal of multi-lead components, removal of remaining component leads	59
Figure K-1 : Removal of flat-pack components	61
Figure L-1 : Soldering of a wrap-around connection to an extended component lead	63
Figure L-2 : Soldering of component lead to a stud lead mounted into an existing hole	64
Figure L-3 : Mounting a dual-in-line package with or without a wire link soldered onto a cropped lead (cropped lead without connection and cropped lead with connection led through hole and onto board).....	65
Figure L-4 : Mounting a dual-in-line package with or without a wire link soldered onto a cropped lead (wire link passing away from board).....	66

Figure L-5 : Mounting a connector with a wire link soldered onto a cropped lead 67

Figure L-6 : Addition of a wire link into a plated through hole occupied by a flat-section lead
(wire link entering from the reverse side of the board) 68

Figure L-7 : Addition of a wire link into a plated through hole occupied by a flat-section lead
(wire link entering from the component side of the board)..... 68

Figure L-8 : Addition of a wire link on top of a flat-pack lead..... 69

Figure L-9 : Isolation of a component lead 71

Figure L-10 : Addition of a wire link onto terminal pad of soldered chips 72

Figure M-1 : Cutting of internal track of a multi-layer circuit board 74

Tables

Table 4-1: Wire diameters for given conductor widths 19